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BERGQUIST GAP FILLER: TGF 2200 APS

Low-Density, Fast-Dispensable Battery Thermal Management Solution

Features & Benefits

- » Silicone-based thermally-conductive liquid Gap Filler
- » Low density
- » Optimized dispensing rate
- » Excellent long-term stability
- » Low compression stress during assembly
- » Low siloxane content (D4-D10)



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Product	Properties	Measurement unit	Typical value	Test methods
BERGQUIST TGF 2200 APS	Thermal conductivity	W/mk	2.2	ASTM D5470
	Density	g/cc	2.05	ASTM D792
	Hardness	Shore OO	55	ASTM D2240
	Viscosity part A	Pa·s	370	ASTM D2196
	Viscosity part B	Pa·s	370	ASTM D2196
	Dielectric strength	KV/mm	9	ASTM D194 DC
	Volume resistivity	Ohm-cm	8.9E+12	ASTM D257
	Application temperature	°C	-40 to 100	NA

TYPICAL APPLICATIONS

- » Automotive power storage
- » Thermal dissipation between battery module and cooling plate
- » Thermal dissipation between any heat-generating semiconductor and heat sink

CONFIGURATIONS AVAILABLE

BERGQUIST Gap Filler TGF 2200 APS is available in the following configurations:

- Cartridges** 400 cc
- Pail kits** 20 liters
- Drum kits** 120 liters

PRODUCT AVAILABILITY

Global

GET IN TOUCH WITH US

Europe

Henkel AG & Co. KGaA
(Headquarters)
Henkelstraße 67
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Asia Pacific

Henkel (China) Investment Co., Ltd.
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